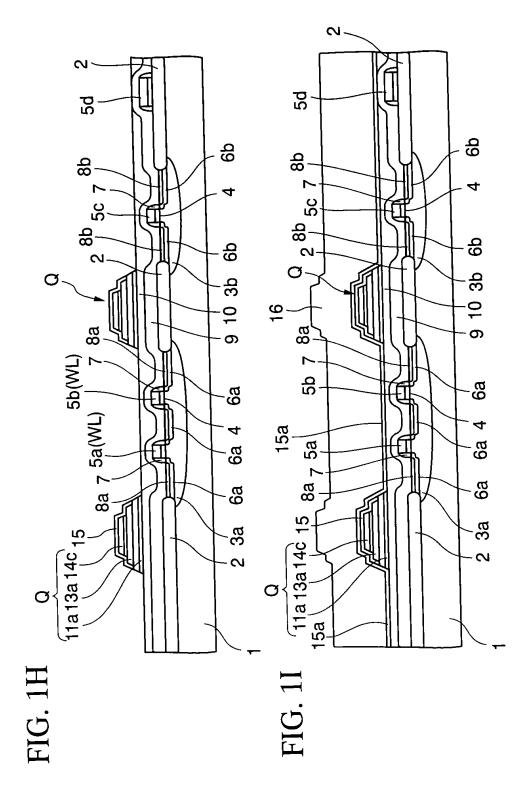
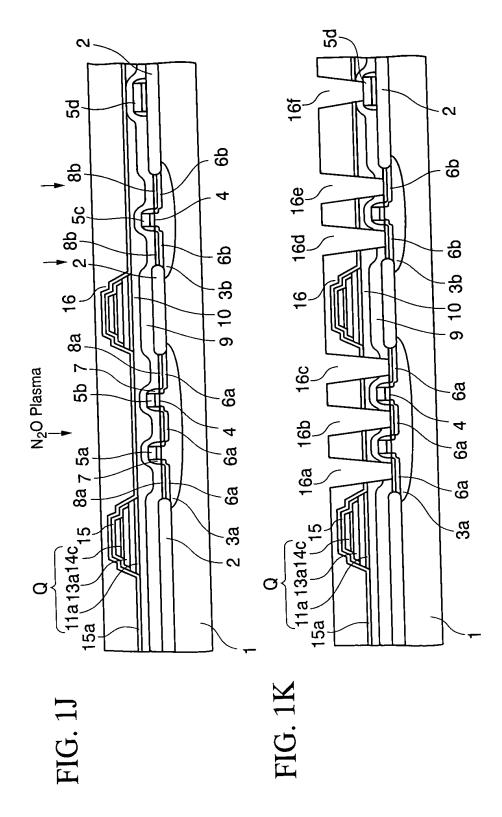
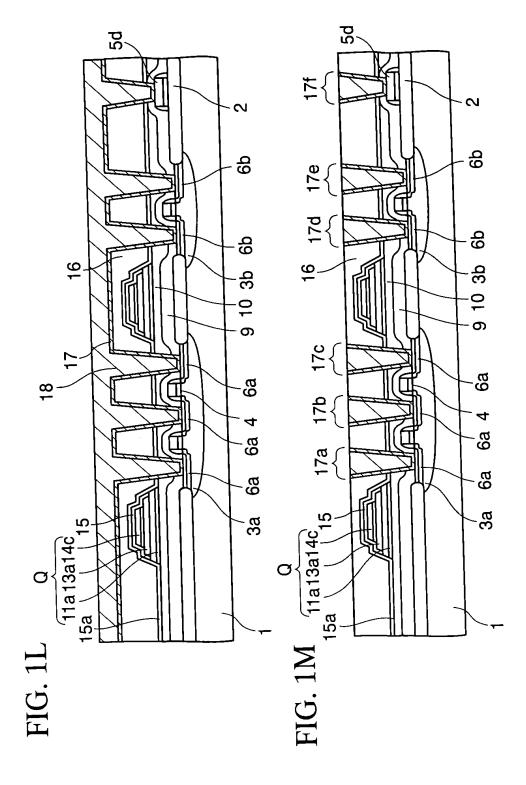


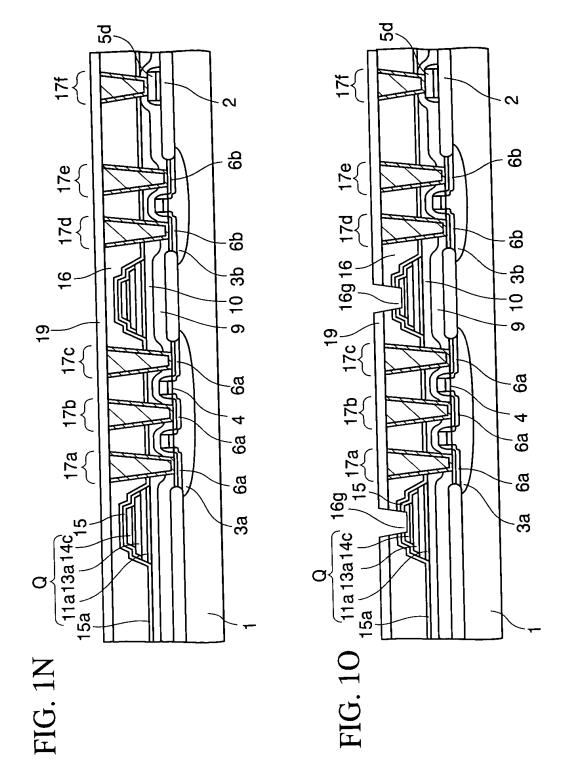
q9 50 8 9  $\alpha$ 14c 13a 36 9 တ 5b(WL) **6**a 5a(WL) 4 6a 8a 3a 2 5

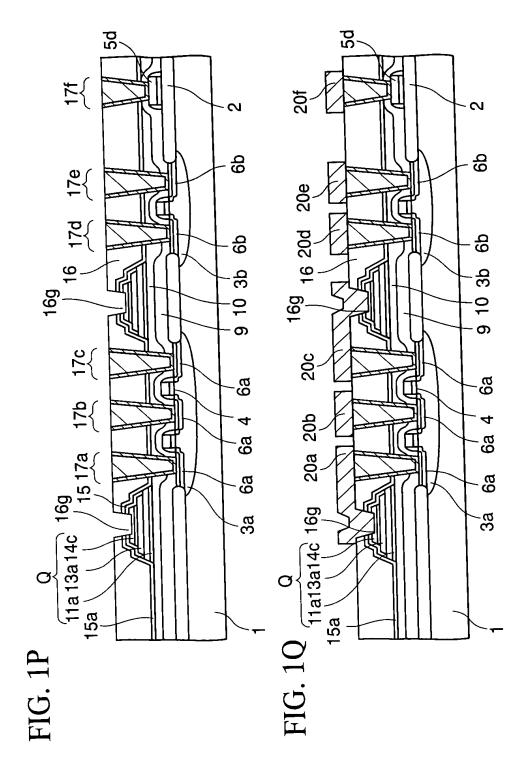
EG. 19

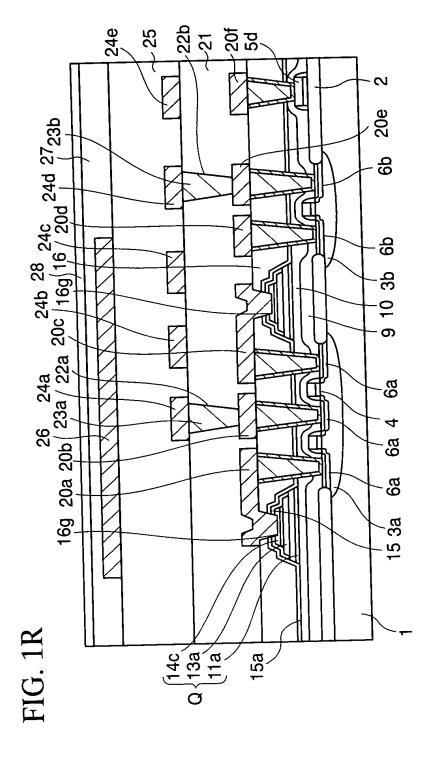












# FIG. 2 (Prior Art)

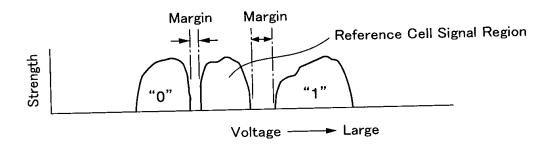


FIG. 3

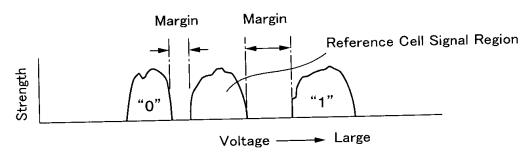
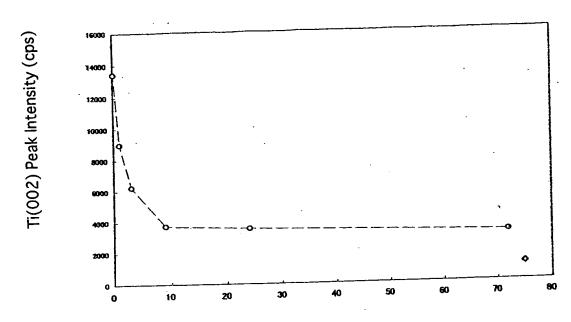


FIG. 4

- o Cen (002)
- No NH<sub>3</sub> Plasma Process Applied Cen (002)



Atmosphere Leaving Time from NH3 Plasma Process to Ti Film Formation (hour)

FIG. 5

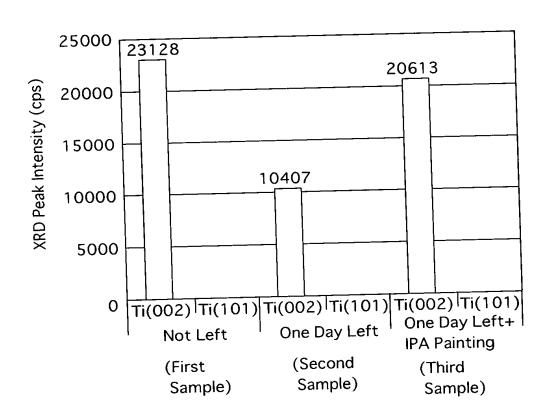


FIG. 6

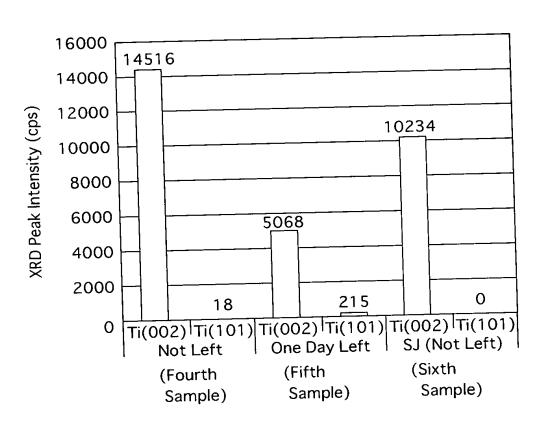


FIG. 7

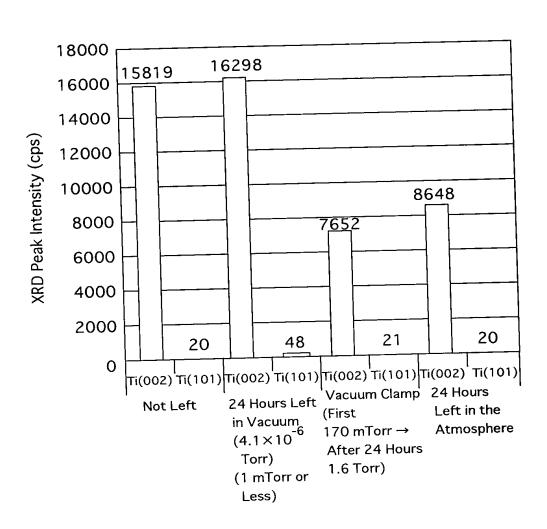


FIG. 8

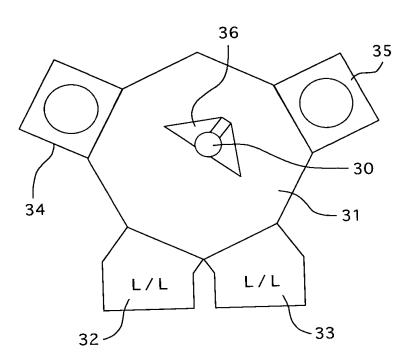


FIG. 9

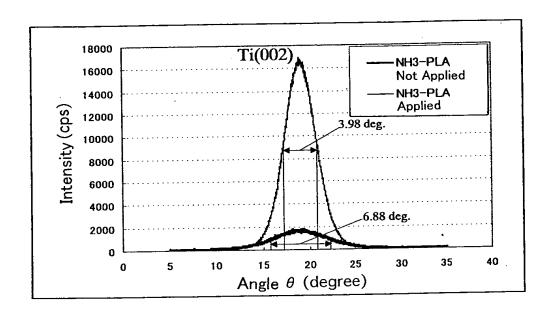


FIG. 10

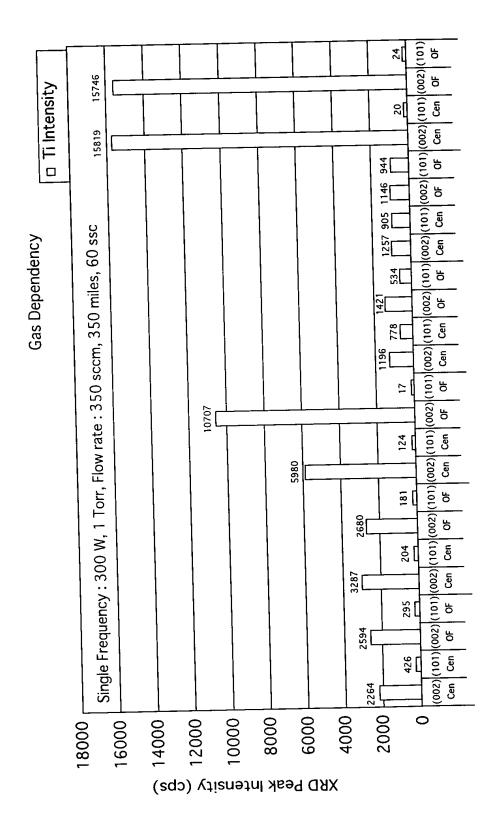
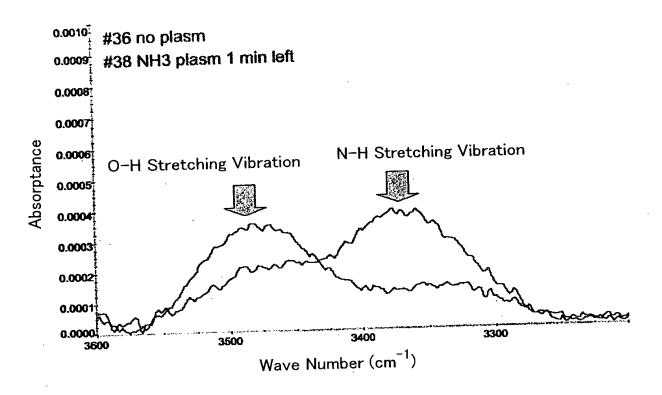


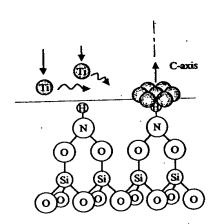
FIG. 11



### FIG. 12A

# Perpendicular Direction to a Substrate Surface O O O O O O Si Si Si Si Si O O

### FIG. 12B





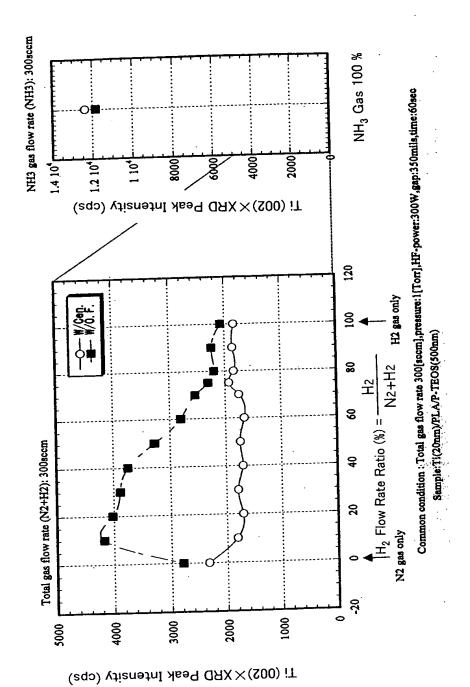
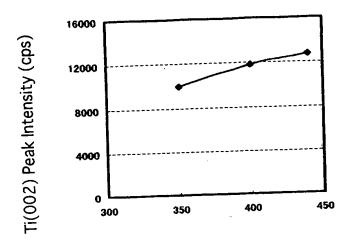
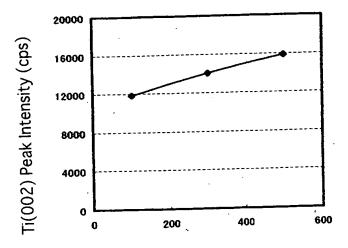


FIG. 14



Set Temperature (°C)

FIG. 15



Power of HF Power Supply (W)

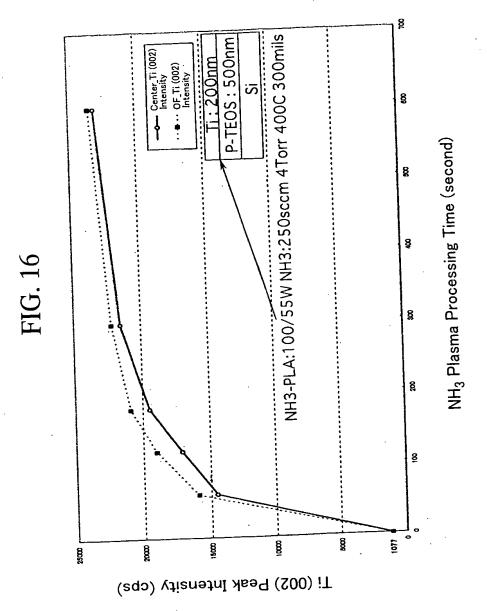
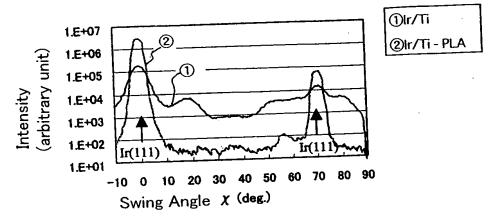


FIG. 17



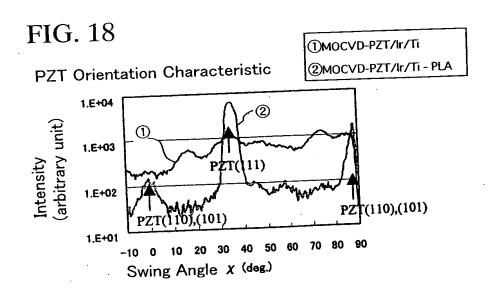


FIG. 19

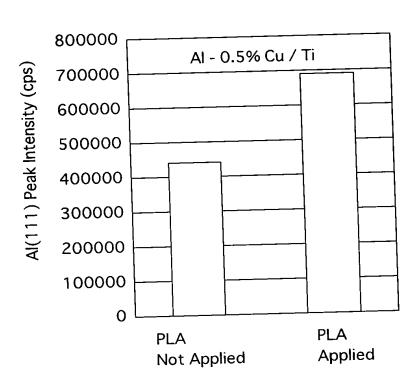


FIG. 20

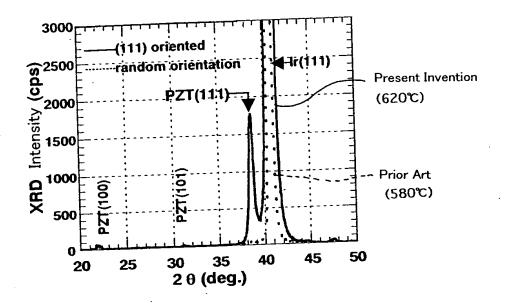


FIG. 21

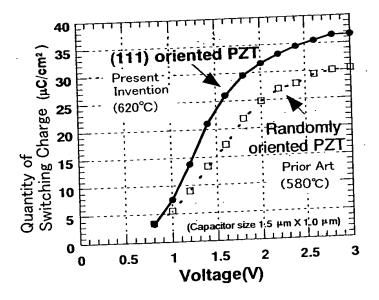


FIG. 22

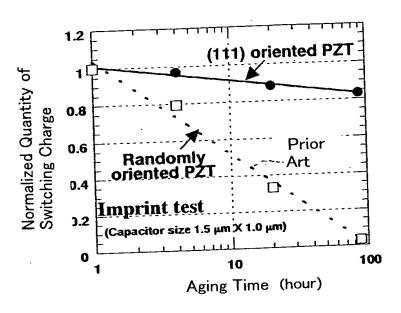


FIG. 23A

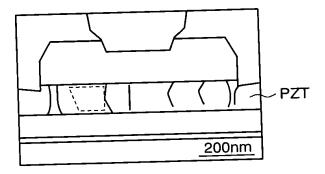


FIG. 23B

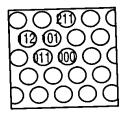


FIG. 24

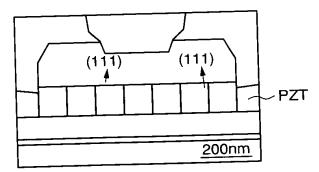


FIG. 25A

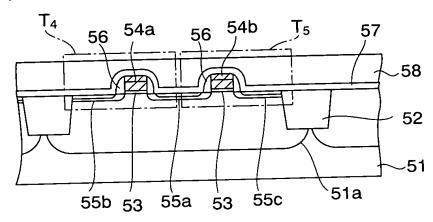


FIG. 25B

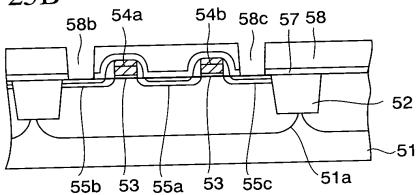


FIG. 25C<sub>60b</sub>

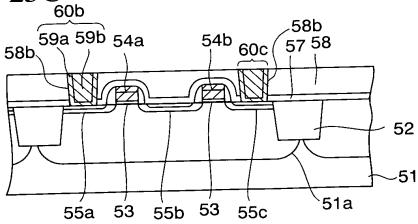


FIG. 25D

### NH<sub>3</sub> Plasma

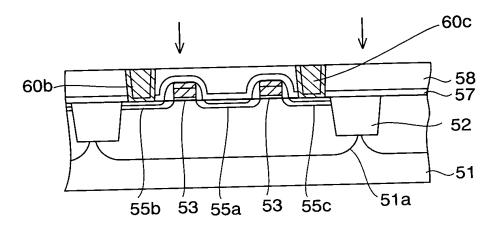


FIG. 25E

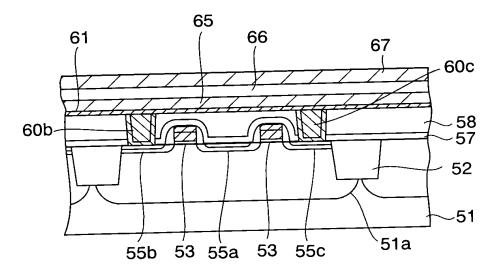


FIG. 25F

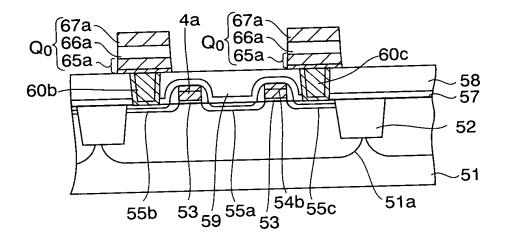


FIG. 25G

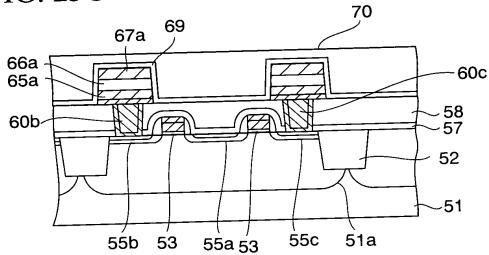


FIG. 25H

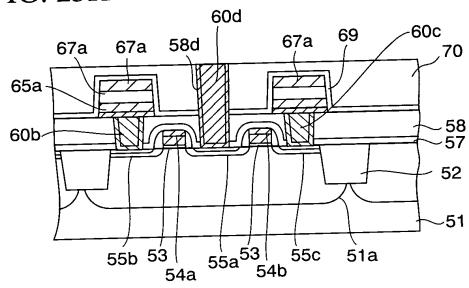


FIG. 25I

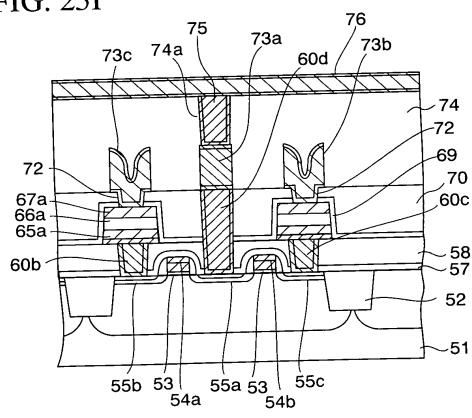
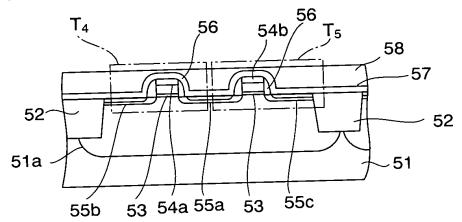


FIG. 26A



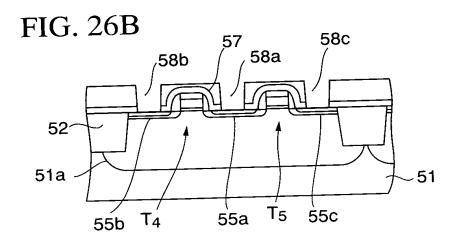
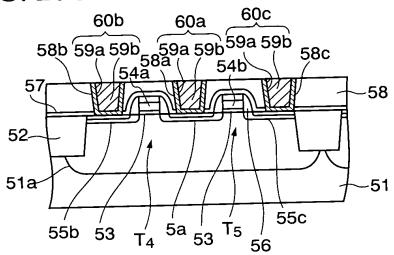


FIG. 26C



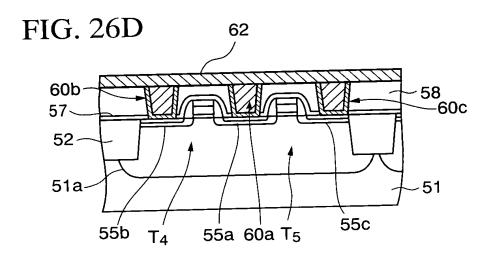
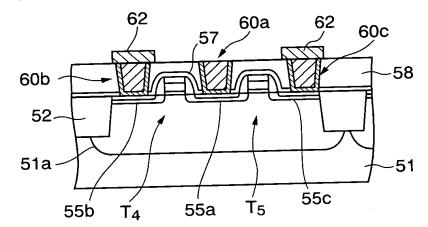
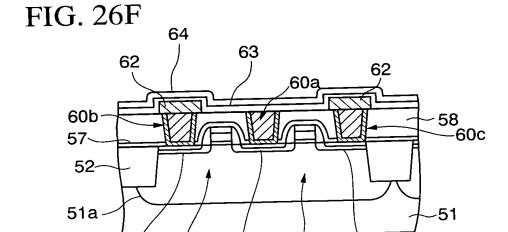


FIG. 26E





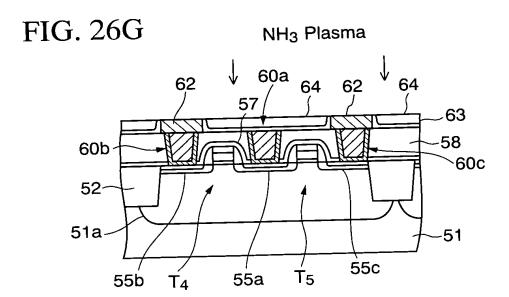
55a

**T**5

55b

**T**4

55c



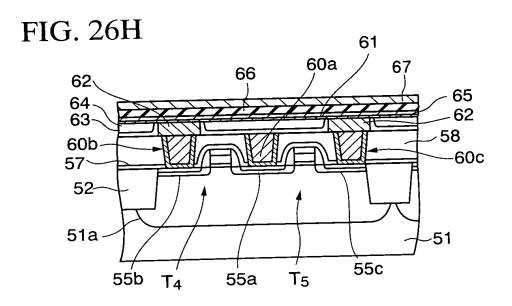
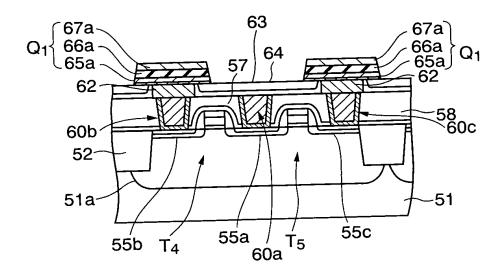


FIG. 26I



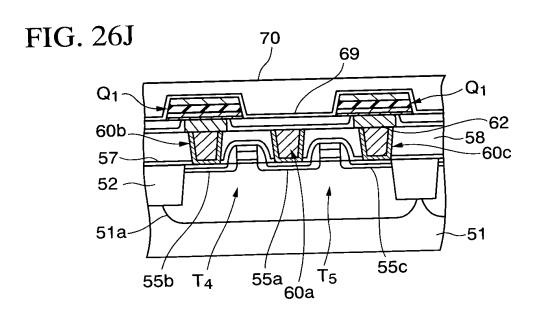


FIG. 26K

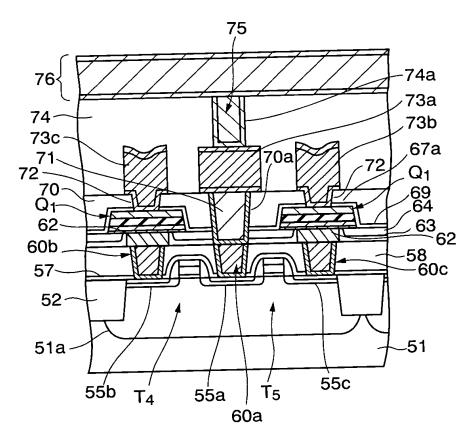
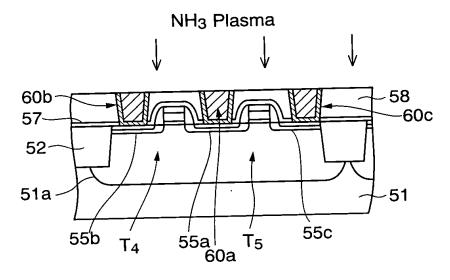


FIG. 27A



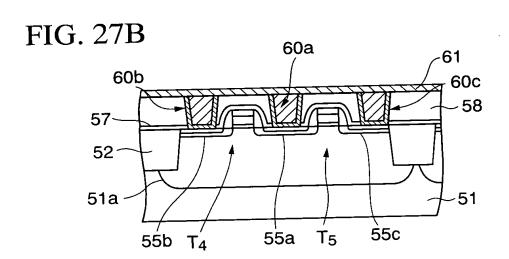


FIG. 27C

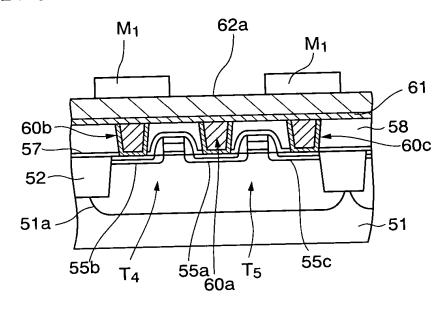


FIG. 27D

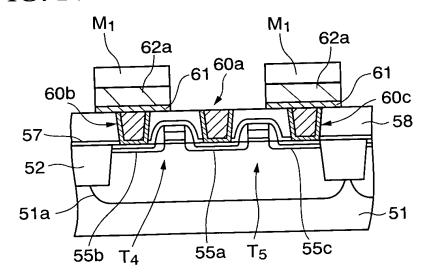


FIG. 27E

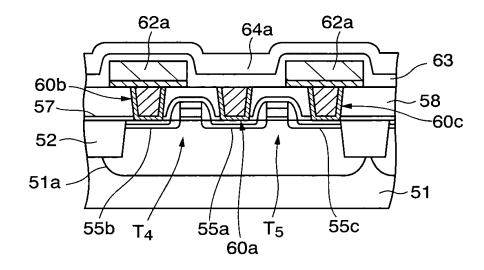


FIG. 27F

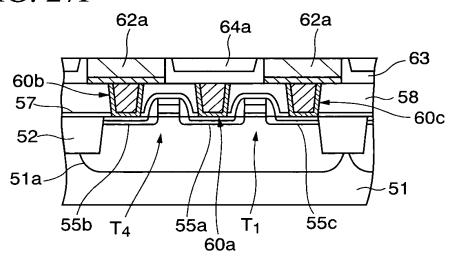


FIG. 27G

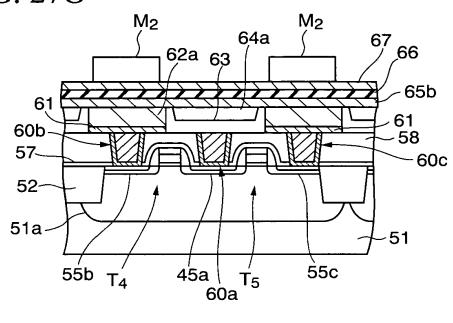
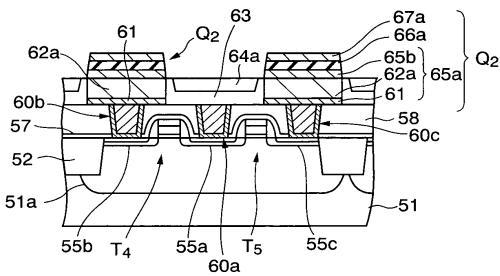


FIG. 27H



## FIG. 27I

